

Final Product Change Notification

Issue Date: 09-Nov-2020 Effective Date: 07-Feb-2021

Dear Emma Tempest,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to <u>view this</u> notification online

This notice is NXP Company Proprietary.

202010023F01



Management Summary

PCA9450 new die A1 version release to replace old die A0 version.

Change Category

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[] Wafer Fab	[] Assembly	[] Product Marking	[] Test	[X] Design
Process	Process		Location	
[] Wafer Fab	[] Assembly	[] Mechanical Specification	[]Test Process	s [] Errata
Materials	Materials			
[] Wafer Fab	[] Assembly	[]	[] Test	[] Electrical spec./Test
Location	Location	Packing/Shipping/Labeling	Equipment	coverage
[] Firmware	[] Other			

FPCN: PCA9450 New Die A1 Version Release.



Description of Change

Dear customer, NXP is replacing the current version of the die (A0) with an A1 variant.

The PCA9450A will be replaced by introducing a PCA9450AA version, while the PCA9450B and the PCA9450C variants will utilize the A1 die.

(the OPN for the AA version can be seen in the parts list, B & C will stay the same and get a rolling update)

Parts list:

PCA9450A replaced by the PCA9450AA (12NC: 9354 101 98518)

PCA9450B (no replacement)

PCA9450C (no replacement)

Reason for Change

NXP observed a "hump" which could occur on buck output voltage in the event when VIN supply is hot plugged off, with peak voltage of about 100mV, and the duration is shorter than 120us. The new version A1 resolves such behavior on buck output.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 22-Nov-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 09-Dec-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Quality Engineer

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NXP Quality Management Team.

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